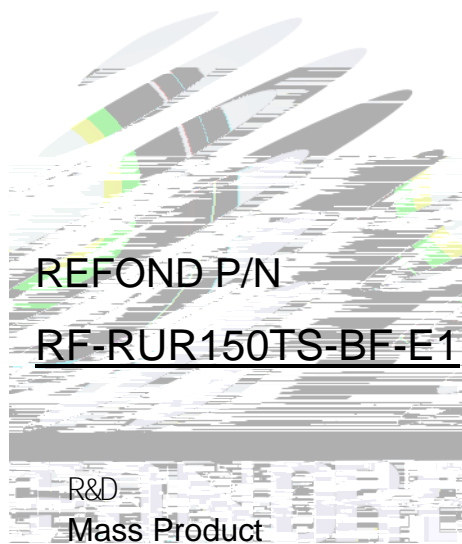
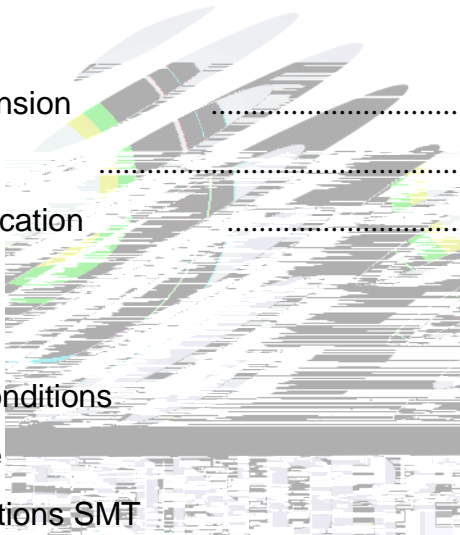


# SPECIFICATION



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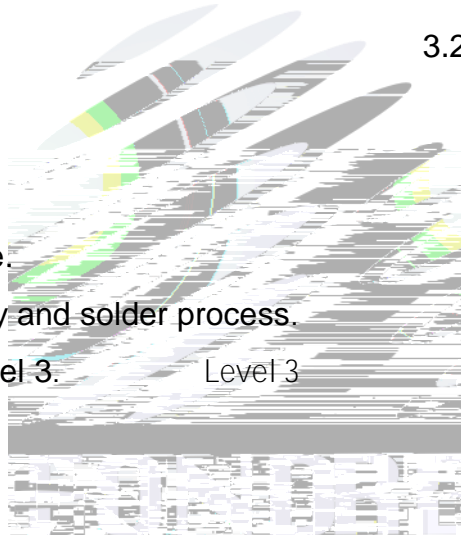
# 1. Description

## 1.1 General Description

The Colour LED which was fabricated using a red chip    Package Dimension :  
 3.2mmX1.25mmX1.1mm.

LED

3.2mmX1.25mmX1.1mm



## 1.2 Features

Extremely wide viewing angle.

Suitable for all SMT assembly and solder process.

Moisture sensitivity level: Level 3.

RoHS compliant.

RoHS

Level 3

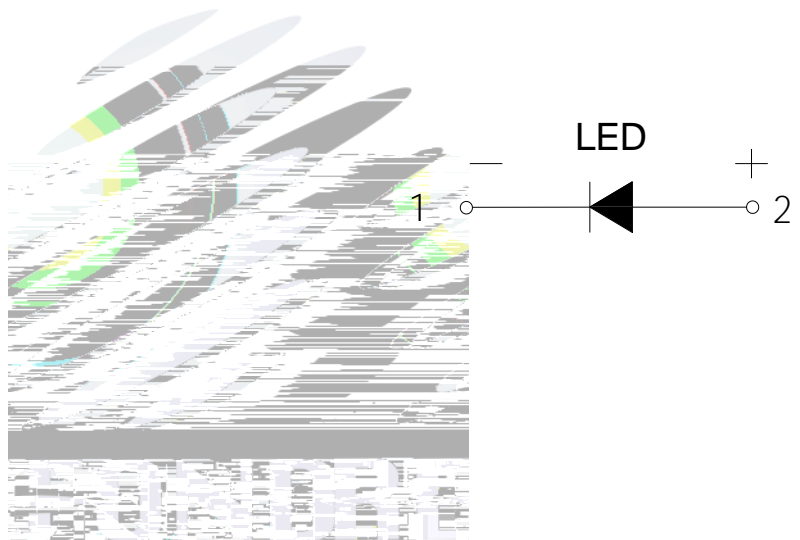
SMT

## 1.3 Application

Optical indicator.

Switch and symbol, display.





## 1.5 Product Parameters

Table 1-1 Electrical / Optical Characteristics at Ts=25°C

Item	Test Condition	Symbol		Value			Unit
				Min. ( )	Typ.	Max.	
Spectral Half Bandwidth	$I_F=20\text{mA}$	$\Delta$		--	15	--	nm
Forward Voltage	$I_F=20\text{mA}$	$V_F$	B0	1.8	--	2.0	V
			C0	2.0	--	2.2	V
			D0	2.2	--	2.4	
Dominant Wavelength	$I_F=20\text{mA}$	$\lambda_D$	F00	625	--	630	nm
			G00	630	--	635	nm
			H00	635	--	640	nm
Luminous Intensity	$I_F=20\text{mA}$	$I_v$		20	--	40	mcd
				40	--	90	mcd
				90	--	140	mcd
				140	--	200	mcd
Viewing Angle	$I_F=20\text{mA}$		--	140	--	deg	
Reverse Current	$V_R=5\text{V}$	$I_R$		--	--	10	A
Thermal Resistance.	$I_F=20\text{mA}$	$R_{THJ-S}$		--	--	450	$^{\circ}\text{C}/\text{W}$

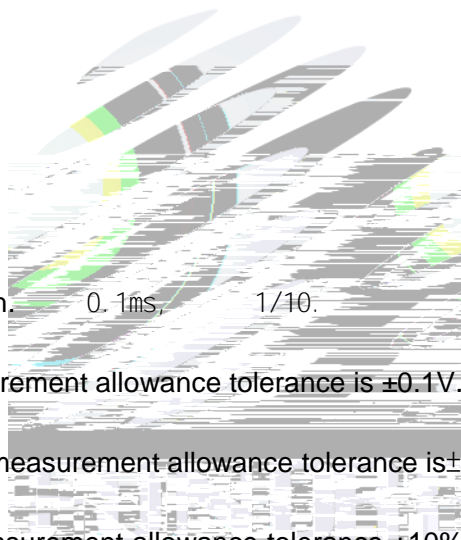
Notes :  $V_R=5\text{V}$  For test conditions.  $V_R=5\text{V}$



Table 1-2 Absolute Maximum Ratings at Ts=25°C

Parameter	Symbol	Rating	Units
Power Dissipation	$P_d$	72	mW

Notes

- 1/10 Duty cycle, 0.1ms pulse width.  0.1ms, 1/10.
2. The above forward voltage measurement allowance tolerance is  $\pm 0.1V$ .  $\pm 0.1V$ .
3. The above dominant wavelength measurement allowance tolerance is  $\pm 2nm$ .  $\pm 2nm$
4. The above luminous intensity measurement allowance tolerance  $\pm 10\%$ .  $\pm 10\%$
5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
6. All measurements were made under the standardized environment of Refond.
7. When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate. LED

## 1.6 Typical Optical Characteristics Curves

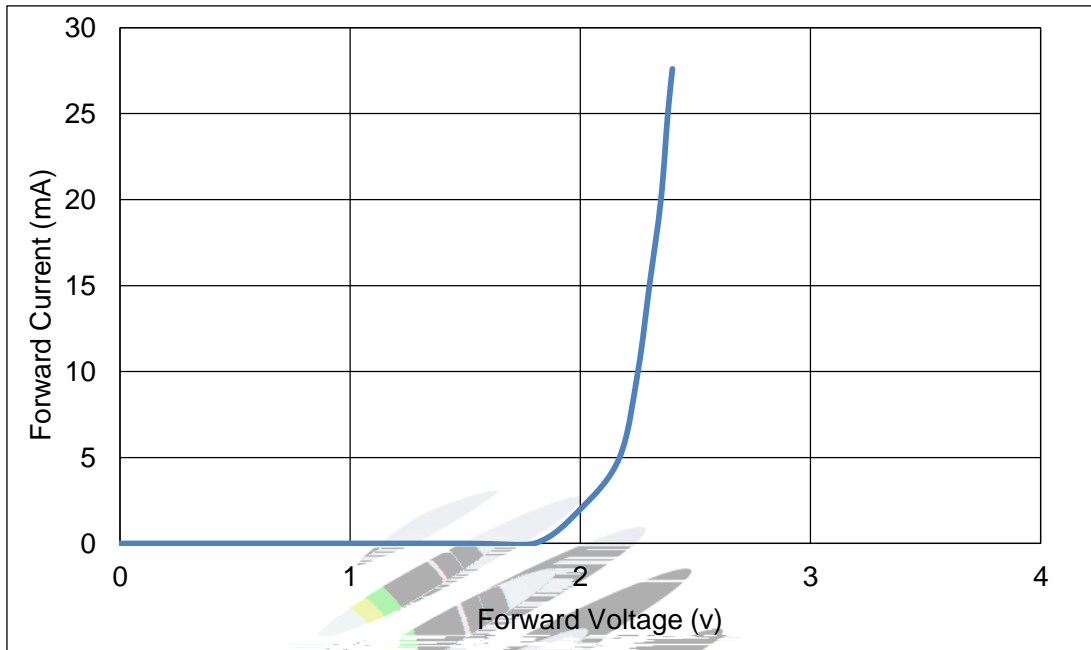


Fig 1-6 Forward Voltage Vs Forward Current

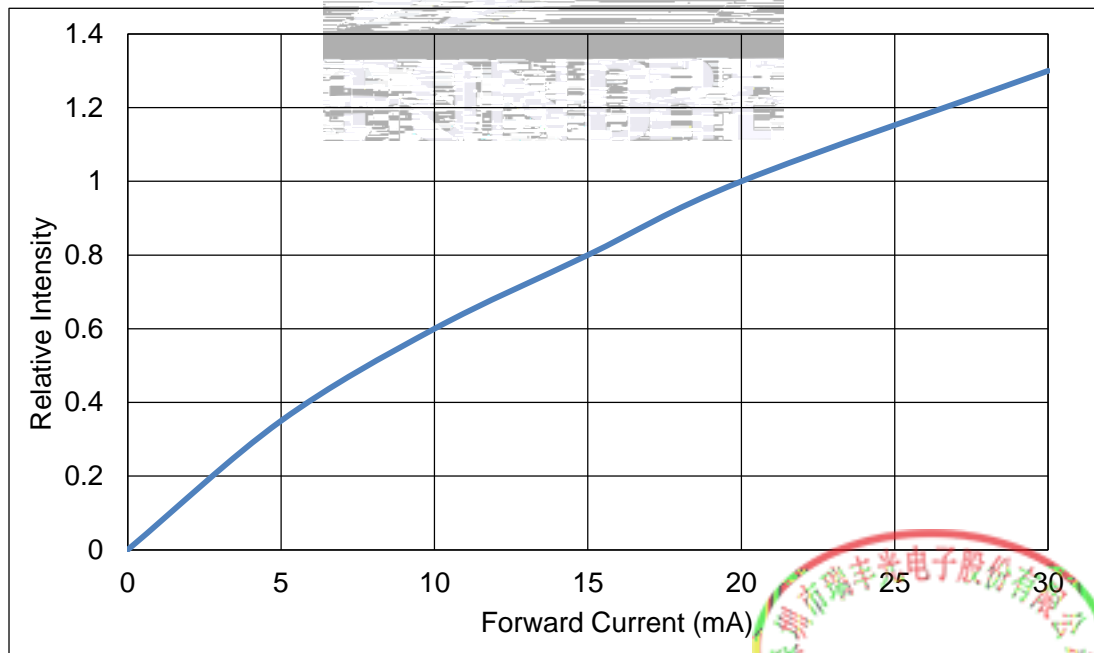
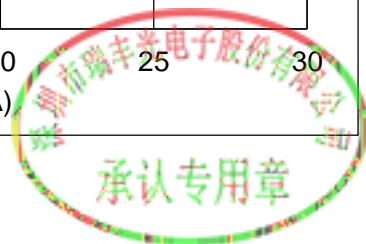


Fig 1-7 Forward Current Vs Relative Intensity



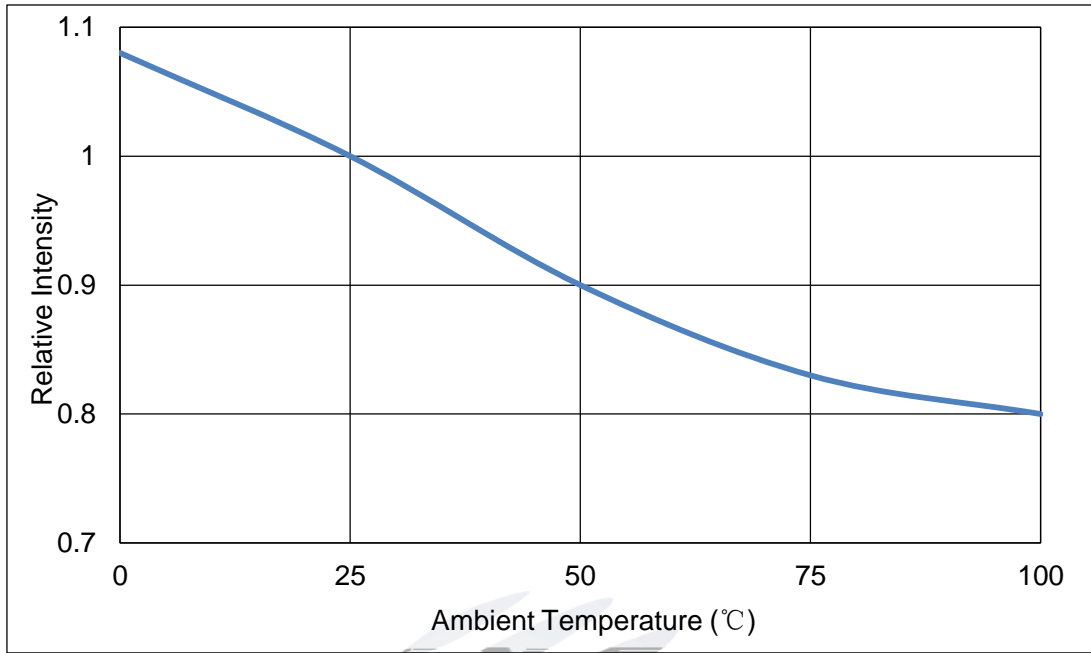


Fig 1-8 Pin Temperature Vs Relative Intensity

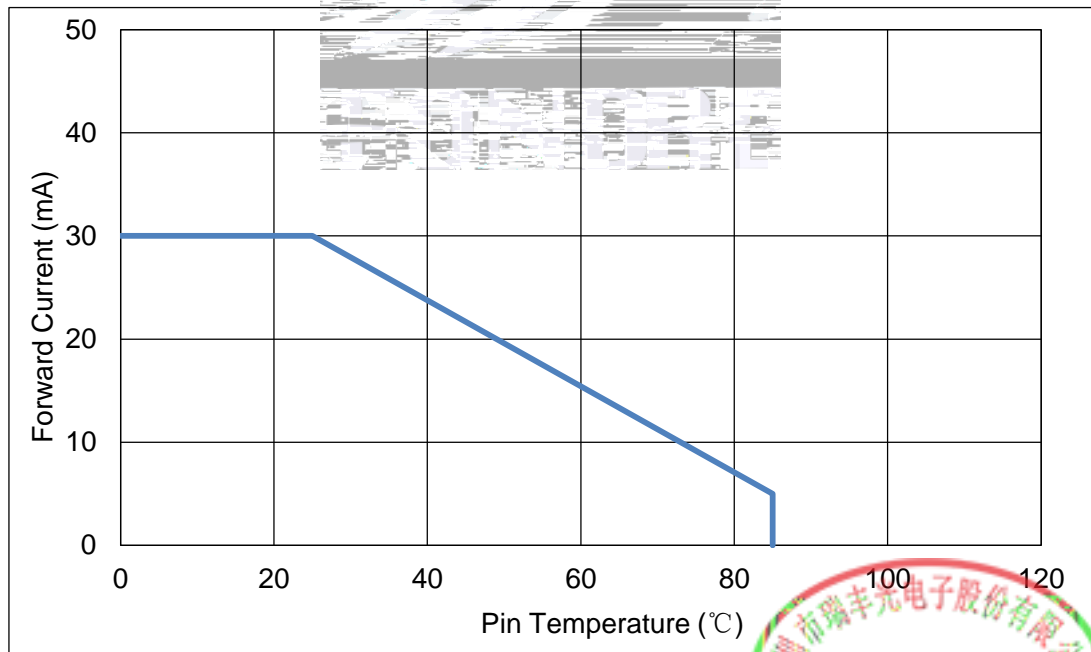
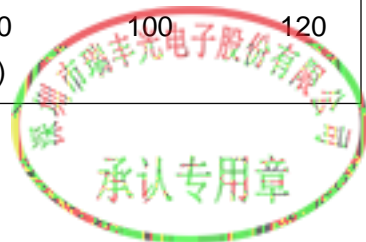
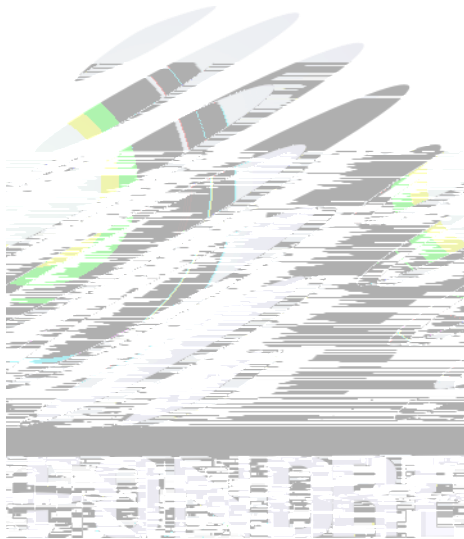


Fig 1-9 Pin Temperature Vs Forward Current







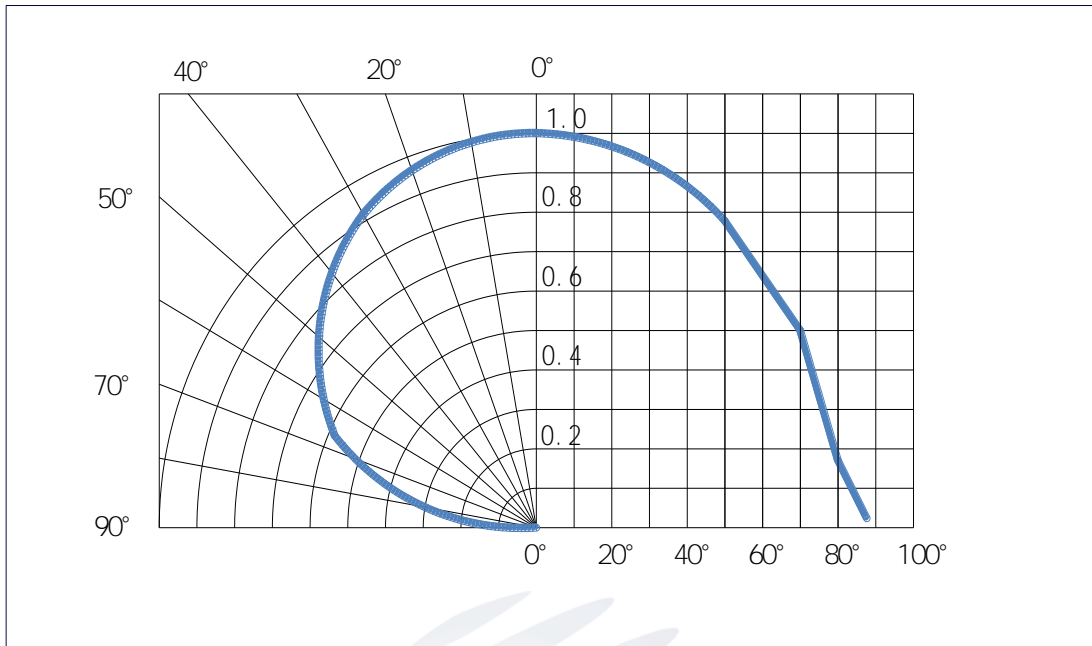
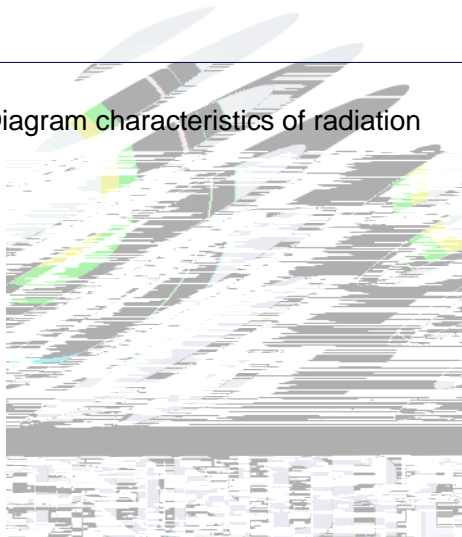


Fig 1-12 Diagram characteristics of radiation



## 2. Packaging

### 2.1 Packaging Specification

Package: 3000pcs/reel.      3000pcs

#### 2.1.1 Carrier Tape Dimension

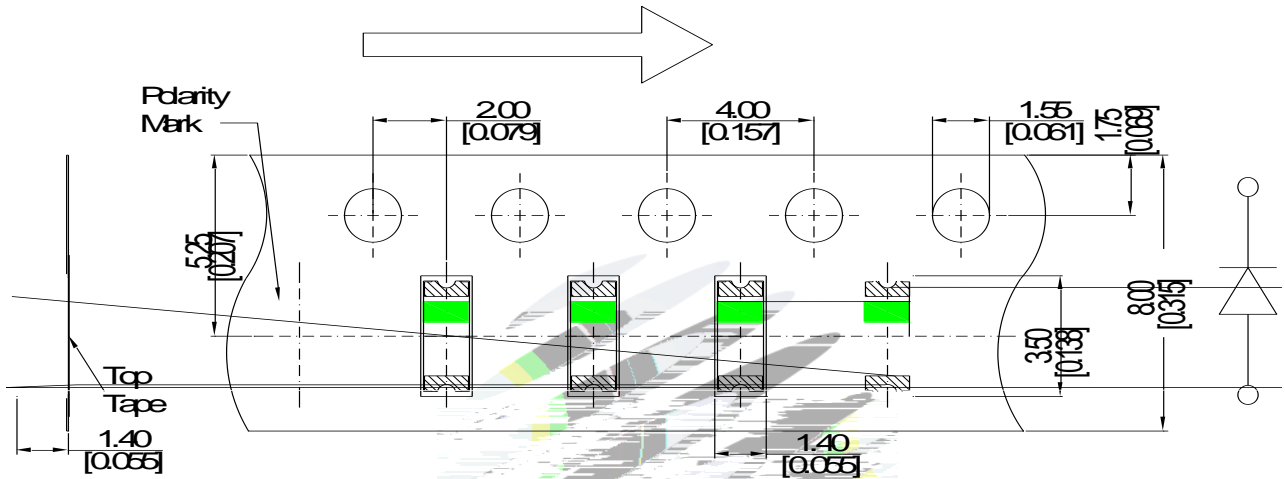


Fig.2-1 Carrier Tape Dimension

#### 2.1.2 Reel Dimension

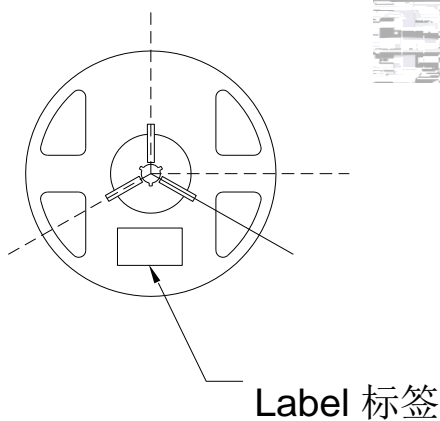


Fig.2-2 Reel Dimension

Table 2-1 Dimension

A	8.0± 0.1mm
B	178± 1mm
C	60± 1mm
D	13.0± 0.5mm

#### Notes

The tolerances unless mentioned  $\pm 0.1\text{mm}$ . Unit : mm



### 2.1.3 Label Form Specification



PART NO:	
SPEC NO:	
LOT NO	
BIN CODE:	
Φ:	XY:
VF:	WLD:
	QTY:
	DATE:

Table 2-2 Parameter

PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code
	Luminous flux
XY	Chromaticity Bin
V <sub>F</sub>	Forward Voltage
WLD	Wavelength
QTY	Packing Quantity
DATE	Made Date

Fig. 2-3 Label Form Specification

### 2.2 Moisture Resistant Packing

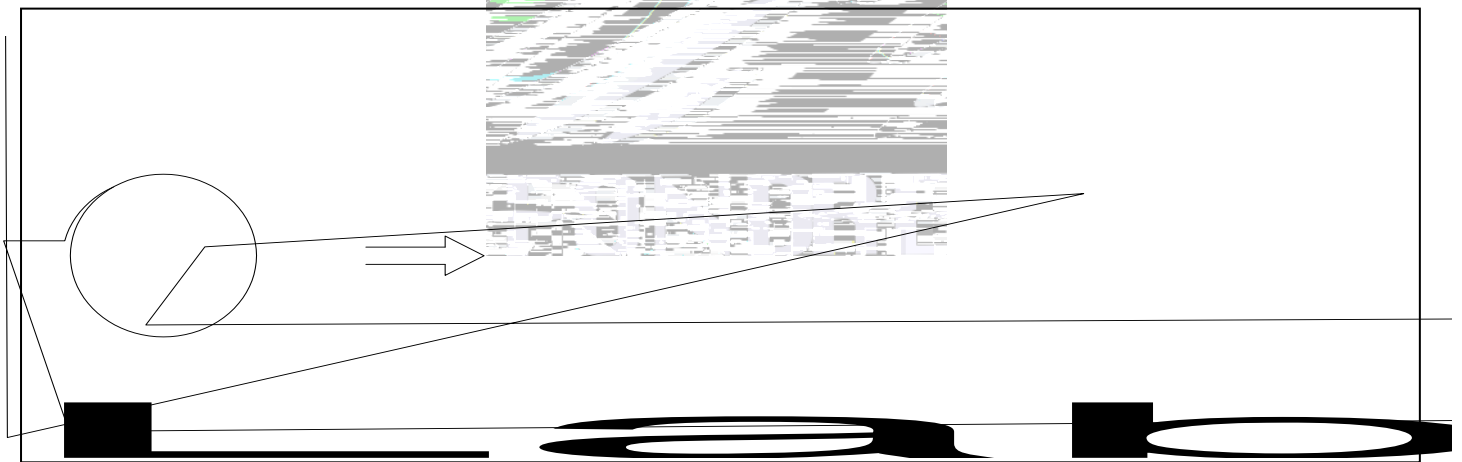


Fig.2-4 Moisture Resistant Packing



## 2.3 Cardboard Box

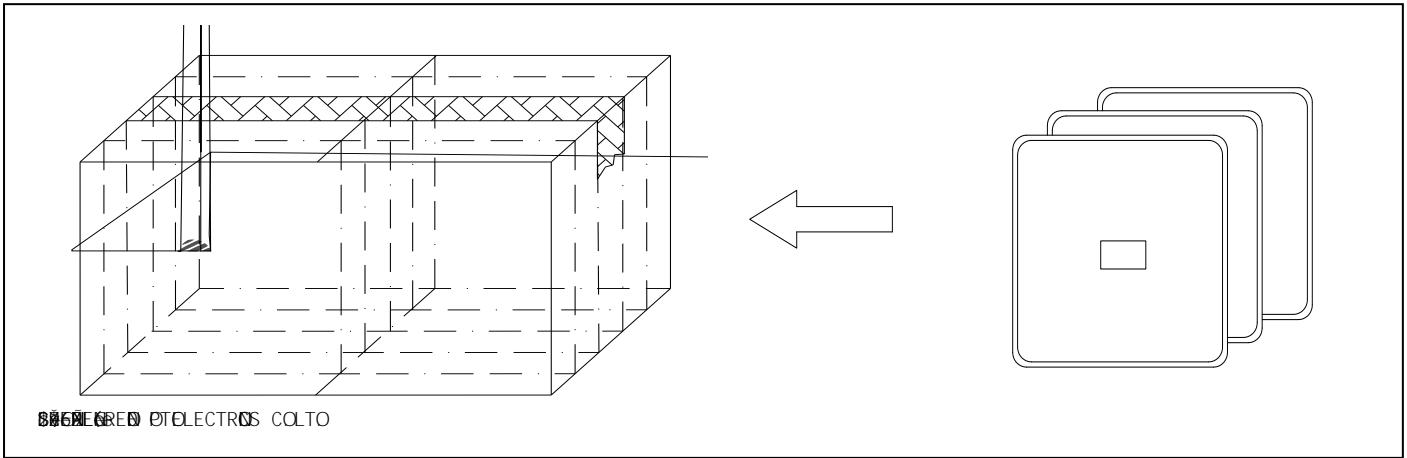
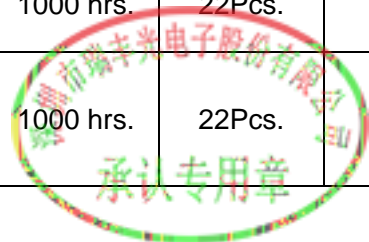


Fig.2-5 Cardboard Box

## 2.4 Reliability Test Items And Conditions

Table 2-3 Reliability Test Items And Conditions

Test Items	Ref.Standard	Test Condition	Time	Quantity	Ac/Re /
Reflow	JESD22-B106	Temp:260 max T=10 sec	2 times	22Pcs.	0/1
Temperature Cycle	JESD22-A104	100 30 min 5 min -40 30 min	100 cycles	22Pcs.	0/1
Thermal Shock	JESD22-A106	-40 15min 100 15min	300 cycles	22Pcs.	0/1
High Temperature Storage	JESD22-A103	Temp:100	1000 hrs.	22Pcs.	0/1
Low Temperature Storage	JESD22-A119	Temp:-40	1000 hrs.	22Pcs.	0/1
Life Test	JESD22-A108	T <sub>a</sub> =25 I <sub>F</sub> =20mA	1000 hrs.	22Pcs.	0/1



## 2.5 Criteria For Judging Damage

Table 2-4 Criteria For Judging Damage

Test Items	Symbol	Test Condition	Criteria For Judgement	
			Min.	Max.
Forward Voltage	$V_F$	$I_F=20\text{mA}$	-	U.S.L*)x1.1
Reverse Current	$I_R$	$V_R= 5\text{V}$	-	U.S.L*)x2.0
Luminous Flux		$I_F=20\text{mA}$	L.S.L*)x0.7	-

### Notes

1.U.S.L: Upper standard level

L.S.L: Lower standard level

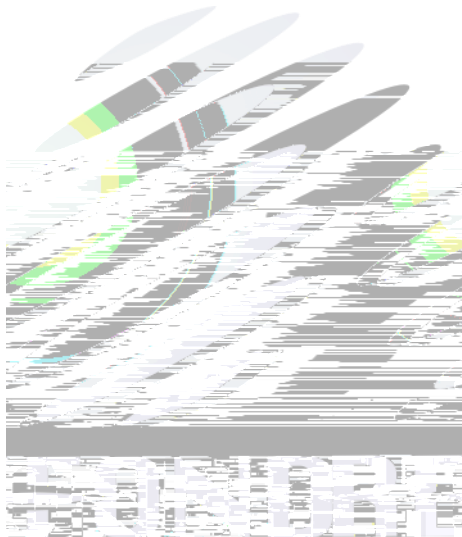
2.The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform,the reliability experiment was taken under good heat dissipation conditions. When customers applies the LED to the series and parallel circuit,should take consideration of all the factors such as the current, voltage distribution, heat dissipation and others.

LED

3.The technical information shown in the data sheets is limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.



### 3. SMT Reflow Soldering Instructions SMT



Notes

(1)Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings , LED will be damaged. 24 LED

(2)Whensoldering , do not put stress on the LEDs during heating.

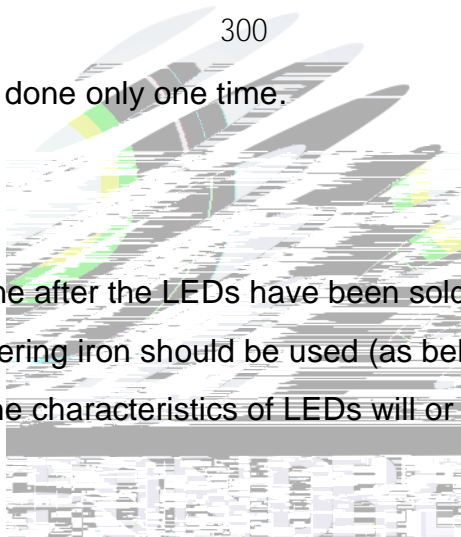
3.1.1 Soldering Iron

(1) When do soldering by hand, keep the temperature of iron below less 300°C less than 3 seconds. 300 3

(2) Soldering by hand should be done only one time.

3.1.2 Repairing

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable,a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.



LED

LED

3.1.3 Cautions

(1) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board.LED PCB

(2) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.





## 4. Handling Precautions

### 4.1 Handling Precautions

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement. LED LED 100PPM.

(2) In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement.

LED LED  
900PPM 900PPM  
1500PPM

(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. Refond advises against the use of any chemicals or materials that have been found or are suspected to have an adverse effect on device performance or reliability. To verify compatibility, Refond recommends that all chemicals and materials be tested in the specific application and environment for which they are intended to be used. Attaching LEDs, do not use adhesives that outgas organic vapor.

LED  
LED

LED



(4) Handle the component along the side surface by using forceps or appropriate tools; Do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.

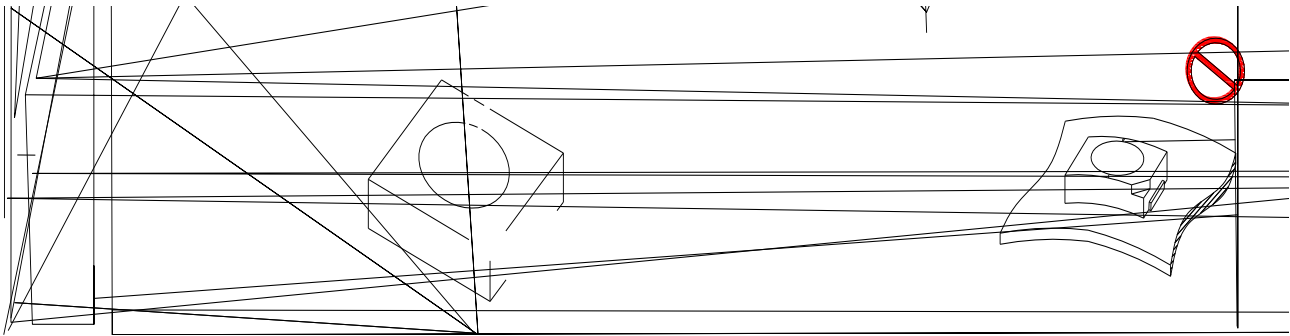
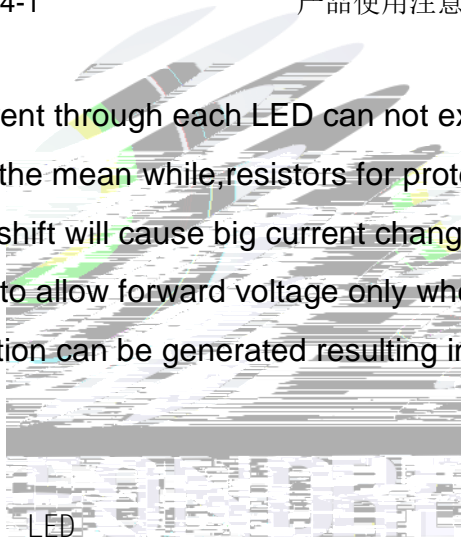


Fig 4-1

产品使用注意事项

(5) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the mean while, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

LED

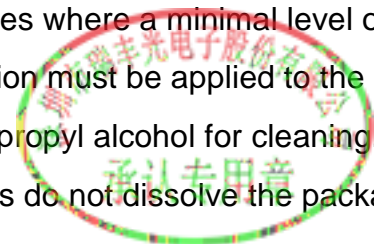


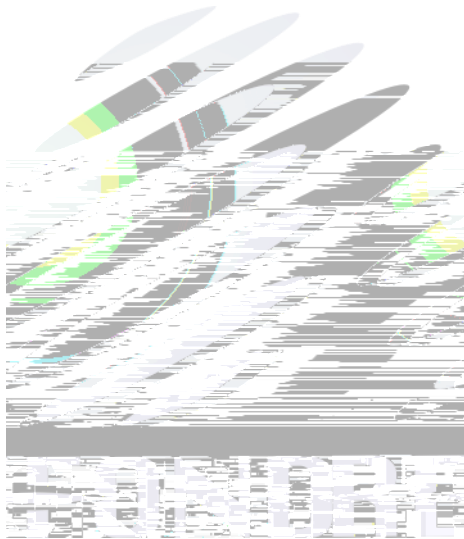
LED

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design. LED

LED

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust, requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or









Declare

This specification is written both in English and in Chinese and the latter is formal.